



2DA1971Q

#### 400V PNP HIGH VOLTAGE SWITCHING TRANSISTOR

#### **Description**

This Bipolar Junction Transistor (BJT) is designed to meet the stringent requirement of Automotive Applications.

#### **Features**

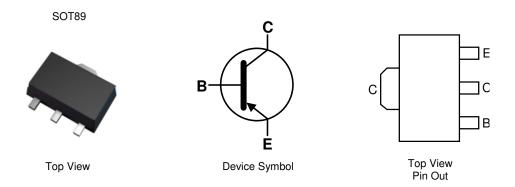
- BV<sub>CEO</sub> > -400V
- I<sub>C</sub> = -0.5A Continuous Collector Current
- I<sub>CM</sub> = -1A Peak Pulse Current
- High Gain Holds up  $h_{FE} \ge 140 @ I_C = -100 mA$
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability
- PPAP Capable (Note 4)

## **Mechanical Data**

- Case: SOT89
- Case Material: Molded Plastic. "Green" Molding Compound. UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish Matte Tin Plated Leads. Solderable per MIL-STD-202, Method 208 @3
- Weight: 0.05 grams (Approximate)

### **Applications**

High Voltage Switching



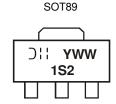
#### Ordering Information (Notes 4 and 5)

Part Number	Compliance	Marking	Reel Size (inches)	Tape Width (mm)	Quantity Per Reel
2DA1971O-7	Automotive	152	7	12	1 000

Notoo:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. Automotive products are AEC-Q101 qualified and are PPAP capable. Refer to https://www.diodes.com/quality/.
- 5. For packaging details, go to our website at https://www.diodes.com/design/support/packaging/diodes-packaging/

#### **Marking Information**



The Manufacturer's Code Marking 1S2 = Product Type Marking Code YWW = Date Code Marking Y = Last Digit of Year (ex: 6 = 2016) WW = Week Code (01 to 53)



## **Absolute Maximum Ratings** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	$V_{CBO}$	-400	V
Collector-Emitter Voltage	$V_{\sf CEO}$	-400	V
Emitter-Base Voltage	$V_{EBO}$	-7	V
Continuous Collector Current	Ic	-0.5	Α
Peak Pulse Current	Ісм	-1	Α
Base Current	Ι <sub>Β</sub>	-250	mA

# Thermal Characteristics (@ $T_A = +25$ °C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Power Dissipation (Note 6)	$P_{D}$	1.5	W
Thermal Resistance, Junction to Ambient (Note 6)	$R_{\theta JA}$	83	°C/W
Thermal Resistance, Junction to Leads (Note 7)	$R_{ heta JL}$	10.4	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

# ESD Ratings (Note 8)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	8,000	V	3B
Electrostatic Discharge - Machine Model	ESD MM	400	V	С

Notes:

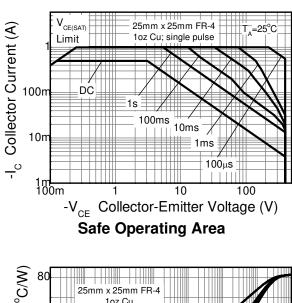
<sup>6.</sup> For a device mounted with the exposed collector pad on 25mm x 25mm 1oz copper that is on a single-sided FR-4 PCB; device is measured under still air conditions whilst operating in a steady-state.

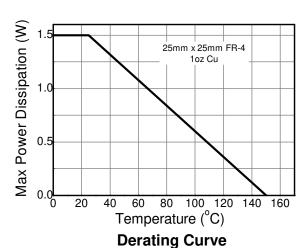
7. Thermal resistance from junction to solder-point (on the exposed collector pad).

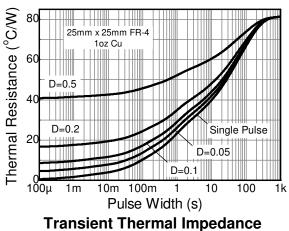
8. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

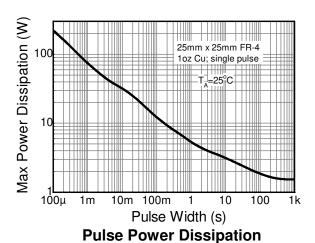


## **Thermal Characteristics and Derating information**











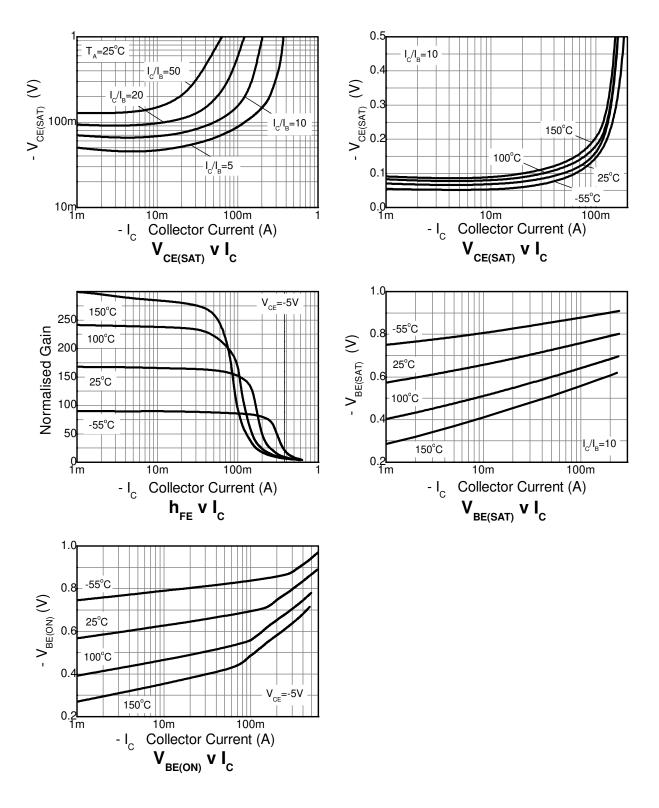
# Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	$BV_{CBO}$	-400	_	_	V	$I_{C} = -100 \mu A$
Collector-Emitter Breakdown Voltage (Note 9)	BV <sub>CEO</sub>	-400	_	_	V	$I_C = -1mA$
Emitter-Base Breakdown Voltage	$BV_{EBO}$	-7	_	_	V	$I_E = -100 \mu A$
Collector-Emitter Cut-off Current	I <sub>CES</sub>	_	_	-100	nA	V <sub>CE</sub> = -320V
Collector Cut-off Current	I <sub>CBO</sub>	_	_	-100	nA	$V_{CB} = -320V$
Emitter Cut-off Current	I <sub>EBO</sub>	_	_	-100	nA	$V_{EB} = -6V$
Static Forward Current Transfer Ratio (Note 9)	h <sub>FE</sub>	140 140	_	450 400	_	I <sub>C</sub> = -20mA, V <sub>CE</sub> = -5V I <sub>C</sub> = -100mA, V <sub>CE</sub> = -5V
Collector-Emitter Saturation Voltage (Note 9)	V <sub>CE(SAT)</sub>	_	_	-250	mV	I <sub>C</sub> = -100mA, I <sub>B</sub> = -10mA
Consider Emiliar Catalation Voltage (Note of				-400		$I_C = -200 \text{mA}, I_B = -40 \text{mA}$
Base-Emitter Saturation Voltage (Note 9)	$V_{BE(SAT)}$	_	-0.75	-0.9	V	$I_C = -100 \text{mA}, I_B = -10 \text{mA}$
Base-Emitter Turn-On Voltage (Note 9)	$V_{BE(ON)}$	_	_	-0.8	V	$I_C = -200 \text{mA}, V_{CE} = -10 \text{V}$
Transition Frequency	f⊤	_	75	_	MHz	$I_C = -50$ mA, $V_{CE} = -5V$ , $f = 50$ MHz
Collector Output Capacitance	$C_{OBO}$	_	19	_	pF	$V_{CB} = -10V, I_{E} = 0, f = 1MHz$
Delay Time	t <sub>(D)</sub>	_	89	_	ns	
Rise Time	t <sub>(R)</sub>	_	111	_	ns	$V_{CC} = -200V$ , $I_{C} = -100mA$ ,
Storage Time	t <sub>(S)</sub>	_	2165	_	ns	$I_{B1} = -10 \text{mA}, I_{B2} = 20 \text{mA}$
Fall Time	t <sub>(F)</sub>	_	185	_	ns	

Note: 9. Measured under pulsed conditions. Pulse width  $\leq$  300 $\mu$ s. Duty cycle  $\leq$  2%.



## Typical Electrical Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

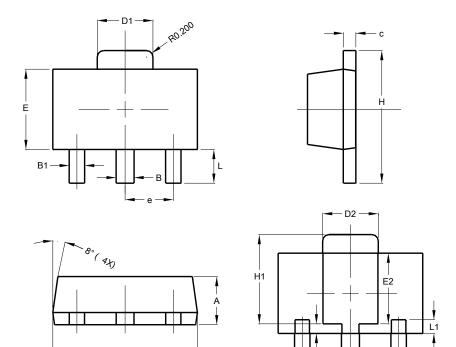




## **Package Outline Dimensions**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### **SOT89**

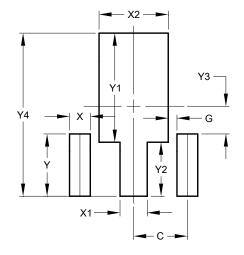


SOT89					
Dim	Min	Max	Тур		
Α	1.40	1.60	1.50		
В	0.50	0.62	0.56		
B1	0.42	0.54	0.48		
С	0.35	0.43	0.38		
D	4.40	4.60	4.50		
D1	1.62	1.83	1.733		
D2	1.61	1.81	1.71		
Е	2.40	2.60	2.50		
E2	2.05	2.35	2.20		
е	-	-	1.50		
Н	3.95	4.25	4.10		
H1	2.63	2.93	2.78		
L	0.90	1.20	1.05		
L1	0.327	0.527	0.427		
Z	0.20	0.40	0.30		
All Dimensions in mm					

## **Suggested Pad Layout**

Please see http://www.diodes.com/package-outlines.html for the latest version.

#### SOT89



Dimensions	Value (in mm)		
С	1.500		
G	0.244		
Χ	0.580		
X1	0.760		
X2	1.933		
Υ	1.730		
Y1	3.030		
Y2	1.500		
Y3	0.770		
Y4	4.530		

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.



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